	Type	Hits	Search Text	DBs
1	BRS	0	US-U5834339-$.DID. OR US-U6107123-$.DID. OR US-U6000924-$.DID. OR US-U6187613-$.DID. OR US-U6255142-$.DID. OR US-U6046076-$.DID.	USPAT
2	BRS	6	US-5834339-$.DID. OR US-6107123-$.DID. OR US-6000924-$.DID. OR US-6187613-$.DID. OR US-6255142-$.DID. OR US-6046076-$.DID.	USPAT
3	BRS	1184304	mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	1904789	encapsulat$6 or resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	23440	(swip$6 or wip$4 or push$4 or pull$4 or forc$4 or thrust$4 or shov$4) near4 (encapsulat$6 or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	1020	((swip$6 or wip$4 or push$4 or pull$4 or forc$4 or thrust$4 or shov$4) near4 (encapsulat$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	4	((swip$6 or wip$4 or push$4 or pull$4 or forc$4 or thrust$4 or shov$4) near4 (encapsulat$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) same stencil$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	28	((swip$6 or wip$4 or push$4 or pull$4 or forc$4 or thrust$4 or shov$4) near4 (encapsulat$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) and stencil$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
9	BRS	27	((((swip$6 or wip$4 or push$4 or pull$4 or forc$4 or thrust$4 or shov$4) near4 (encapsulat$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) and stencil$4) and ((@ad < "20030312")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	621778	squeege or wiper or swiper or blade	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	4278	(squeege or wiper or swiper or blade) near4 (encapsulat$6 or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	2	(((squeege or wiper or swiper or blade) near4 (encapsulat$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) and stencil$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	114	(((squeege or wiper or swiper or blade) near4 (encapsulat$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	633	(squeege or wiper or swiper or blade) same (encapsulat$6 or resin) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	BRS	598	(((squeege or wiper or swiper or blade) same (encapsulat$6 or resin) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))) and (@ad < "20030312")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
16	BRS	103	(squeege or wiper or swiper or blade) near8 (encapsulat$6 or resin) near8 (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17	BRS	96	((squeege or wiper or swiper or blade) near8 (encapsulat$6 or resin) near8 (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))) and (@ad < "20030312")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18	BRS	626400	squeege or wiper or swiper or blade or sweeper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19	BRS	103	(squeege or wiper or swiper or blade or sweeper) near8 (encapsulat$6 or resin) near8 (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20	IS&R	1499	((438/112) or (438/124) or (438/126)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
21	BRS	1323	(((438/112) or (438/124) or (438/126)).CCLS.) and (@ad < "20030312")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	BRS	105	(((((438/112) or (438/124) or (438/126)).CCLS.) and (@ad < "20030312")) and (squeege or wiper or swiper or blade or sweeper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
23	BRS	103	(((((438/112) or (438/124) or (438/126)).CCLS.) and (@ad < "20030312")) and (squeege or wiper or swiper or blade or sweeper)) not (((squeege or wiper or swiper or blade) near8 (encapsulat$6 or resin) near8 (mcm or multi adj chip or multi-chip" or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))) and (@ad < "20030312"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB